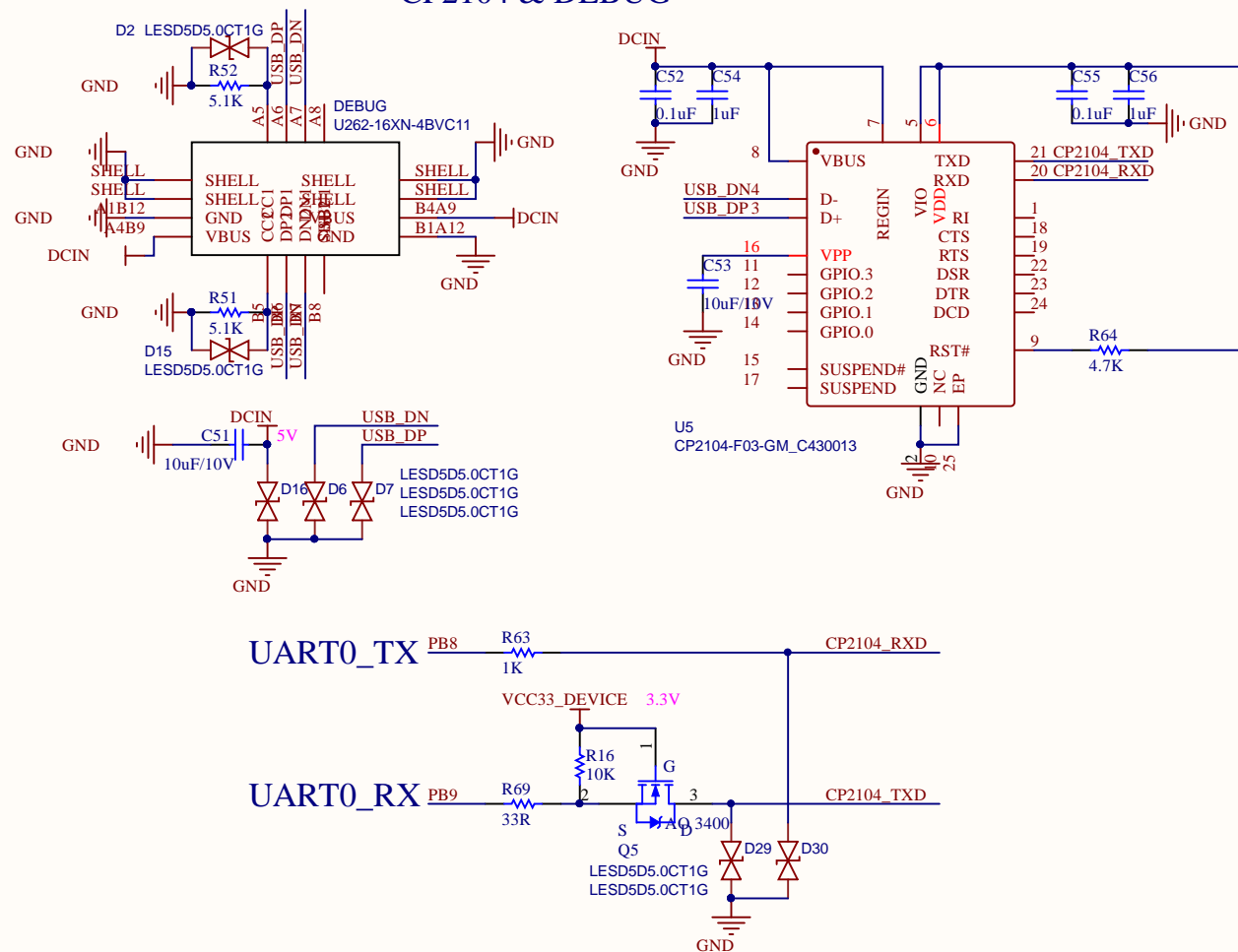
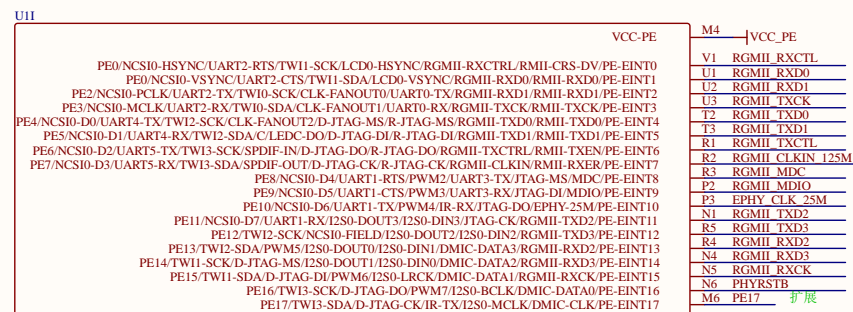
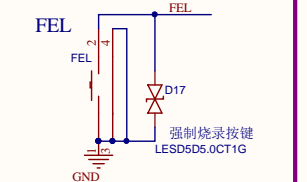
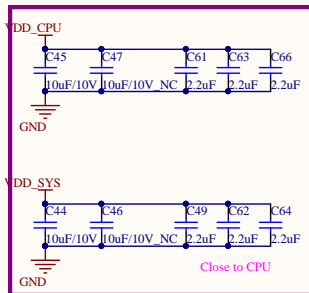


## CP2104 &amp; DEBUG

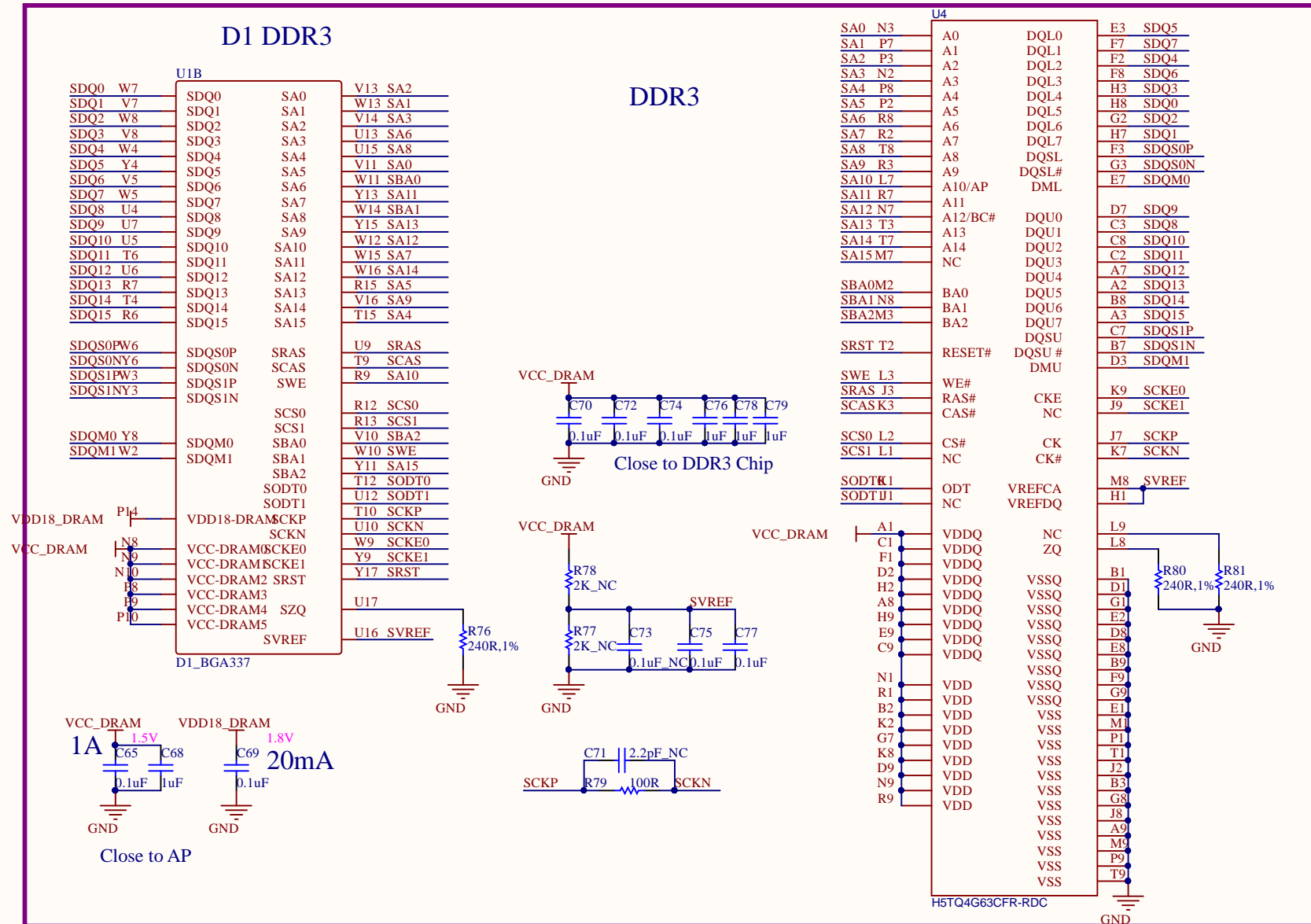


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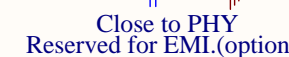
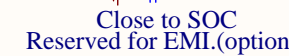


## D1 DDR3

## DDR3

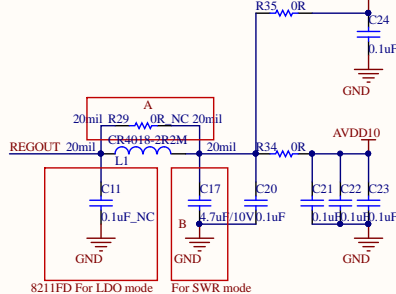
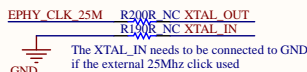


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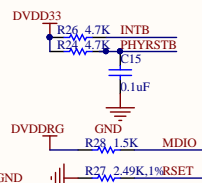
- Note1:RE10 is not needed for only 3.3v RGMII application,  
and DVDDRG can be connected directly to DVDD33  
Note2:DVDDRG must be short(or RE10 be mounted) to  
DVDD33 if the external RGMII 3.3V is selected  
Note3:RE10 must be removed if the internal or external  
2.5V/1.8V/1.5V RGMII is selected  
Note4:CAPs must be closed to pin28 for EMI consideration

### External Clock Case



- Note1:Bypass CAPs close PHY DVDD10/AVDD10 power pins  
 Note2:Any inductance or bead except L1 is not allowed on the path from REGOUT to DVDD10/AVDD10  
 Note3:A is reserved to change th DVDD10/AVDD10 supply source to LDO mode(RTL8211FID)  
 Note4:No design change of PCB model is need if A is reserved.If only RTL8211FID used for particular PCB model,directly short REGOUT to DVDD10/AVDD10  
 Note5:If RTL8211FI is selected,the B should be replaced as 10uF X7R capacitor for industrial grade application,Please refer to the datasheet for other industrial grade information

## PHY RESET/INTB

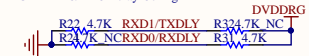


### Enable/Disable PLL @ALDPS

R23 4.7K RXD2/PLLOFF R334

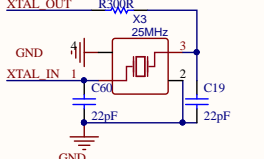
### Pull-up to disable PLL@ALDPS

### RGMII TXC/RXC Delay Config



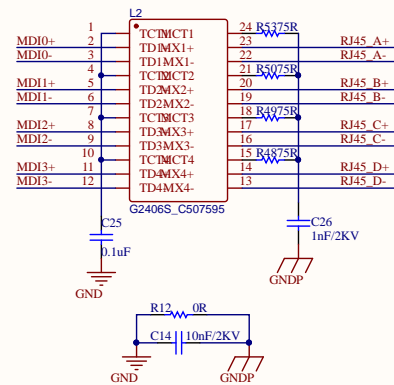
all-up for additional 2ns delay to TXC/RXC for data latching.

## Crystal Case

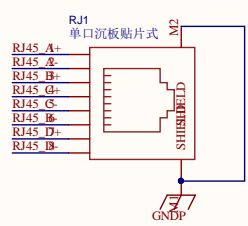


# Transformer

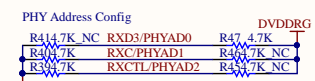
Differential pairs  
Z0=100 OHM



## RJ45

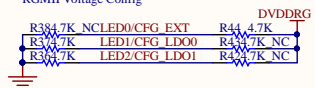


U3		GND	
MDIO+	1	MDIP0	AVDD33
MDIO-	2	MDIN0	RSET
MDVD10	3	AVDD10	AVDD10
MDI1+	4	MDIP1	XTAL_OUT/EXT_CLK
MDI1-	5	MDIN1	XTAL_IN
MDI2+	6	MDIP2	CLKOUT
MDI2-	7	MDIN2	CFG_LD0/LD2
AVDD10	8	AVDD10	CFG_LD00/LD1
MDI3+	9	MDIP3	CFG_EXT/LED0
MDI3-	10	MDIN3	INTB/PMB
AVDD33	11	AVDD33	REG_OUT/LDO_OUT
PHYRSTB	12	PHYRSTB	DVDD33
MDC	13	MDC	DVDD_RG
MDIO	14	MDIO	PHYAD1/RXC
TXD3	15	TXD3	PHYAD2/RXCTL
TXD2	16	TXD2	RXDLY/RXD0
TXD1	17	TXD1	TXDLY/RXD1
TXD0	18	TXD0	PLOFF/RXD2
TXCTL	19	TXCTL	PHYAD0/RXD3
TXC	20	TXC	DVDD10



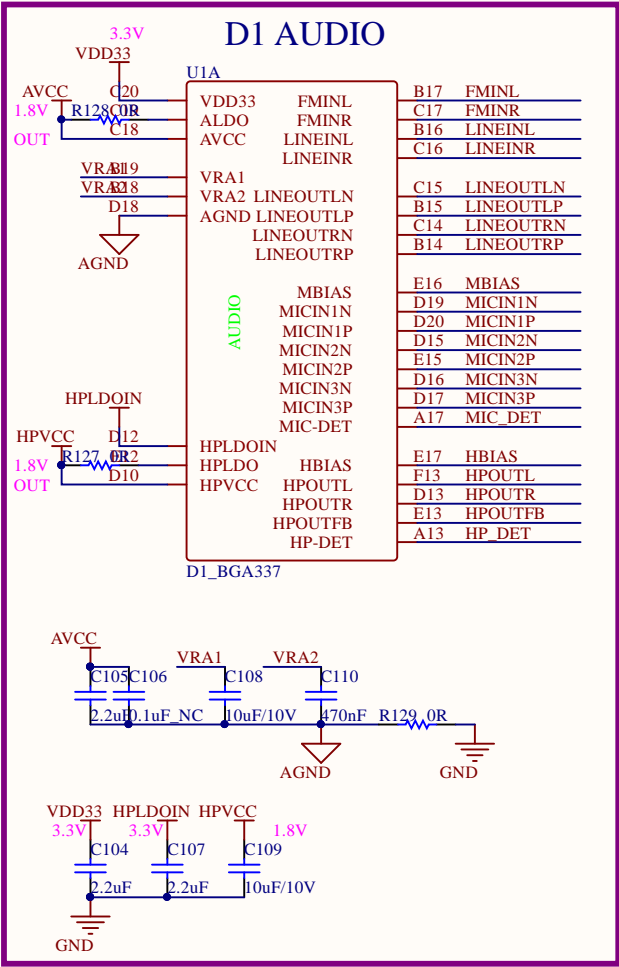
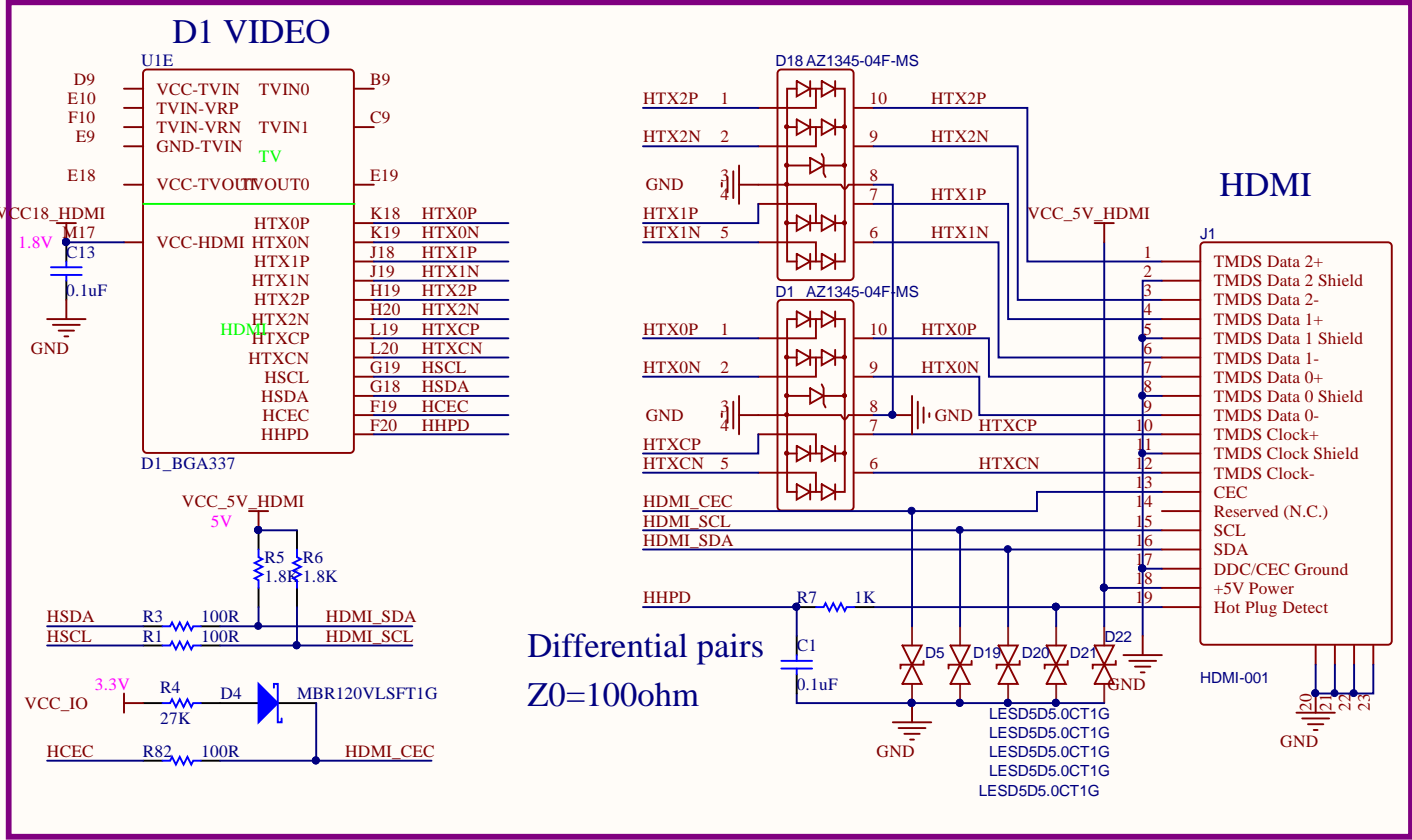
PHY Address	PHY AD[2:0]
0	3'b000
1(default)	3'b001
2	3'b010
3	3'b011
4	3'b100
5	3'b101
6	3'b110
7	3'b111

### RGMII Voltage Config

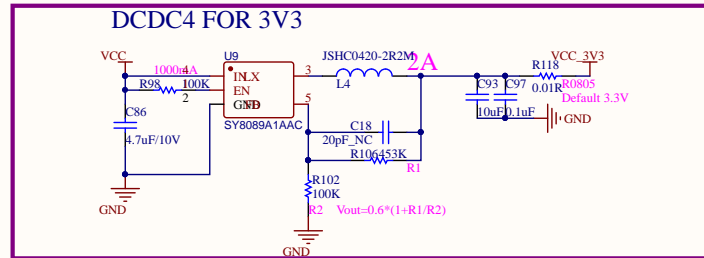
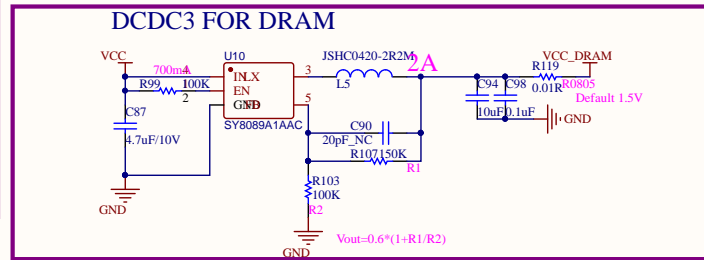
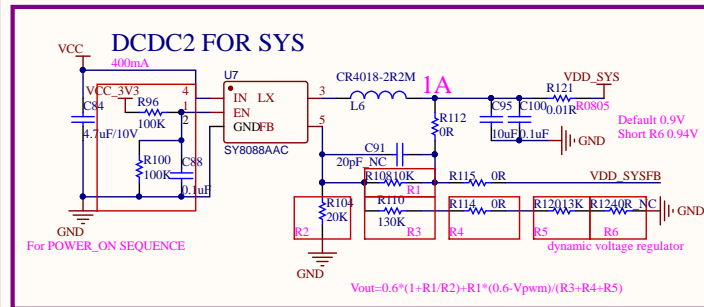
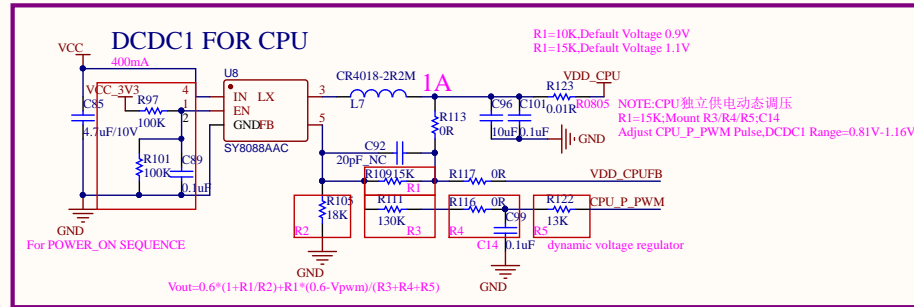
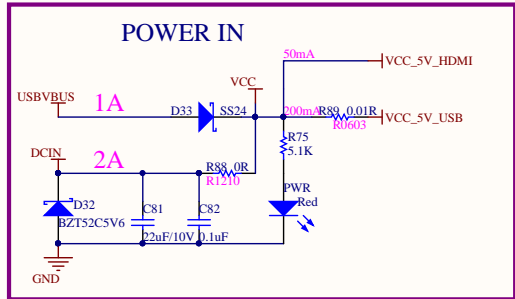
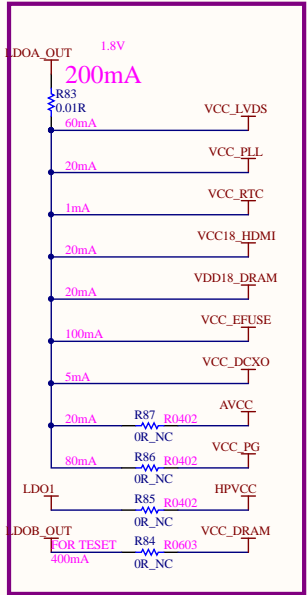
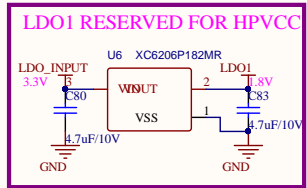


RGMIIPower Source	CFG_EXT	CFG_LDO[1:0]
External 3.3V(default)	1'b1	2'b00
External 2.5V	1'b1	2'b01
External 1.8V	1'b1	2'b10
External 1.5V	1'b1	2'b11
Internal 2.5V	1'b0	2'b01
Internal 1.8V	1'b0	2'b10
Internal 1.5V	1'b0	2'b11

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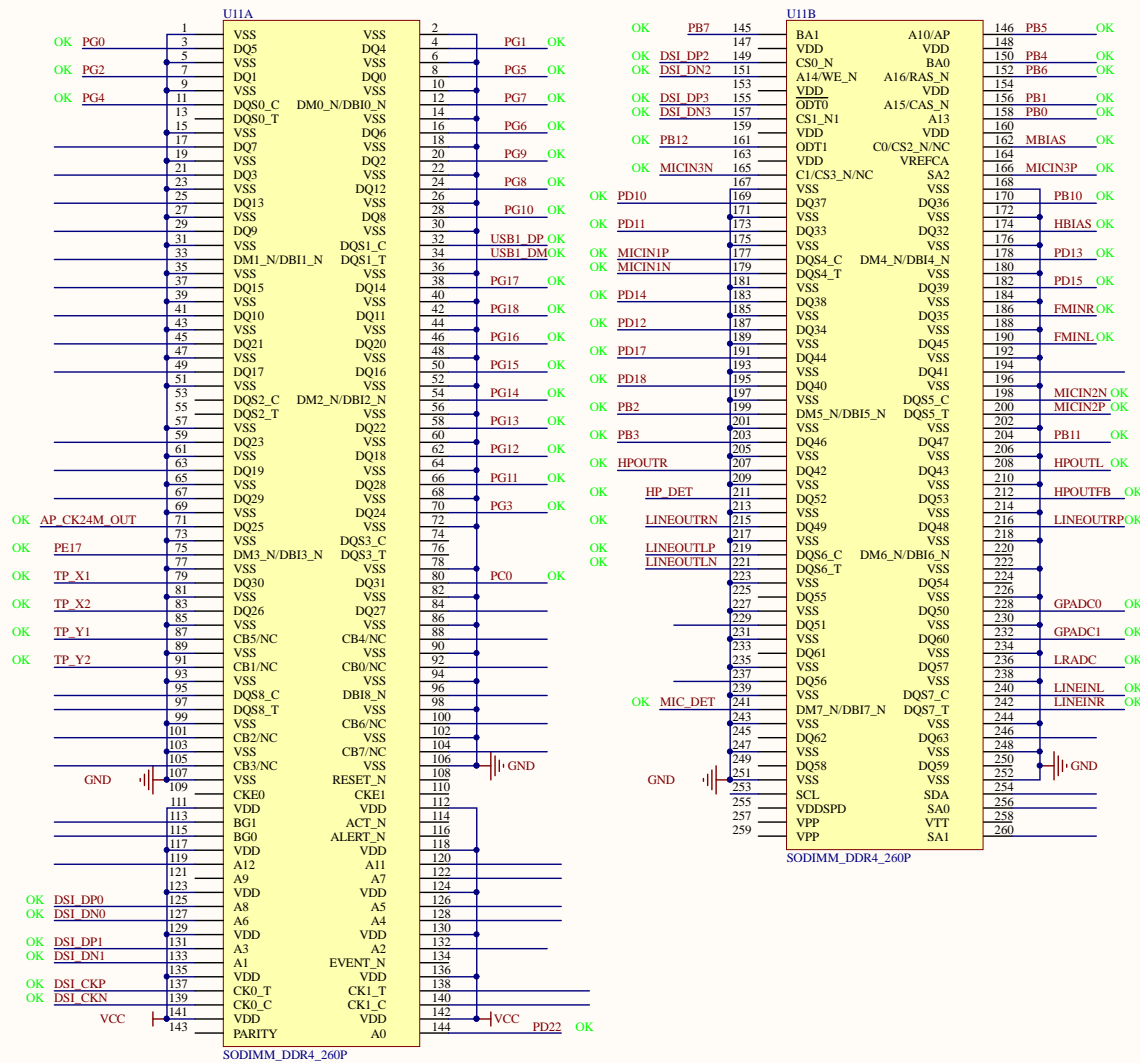


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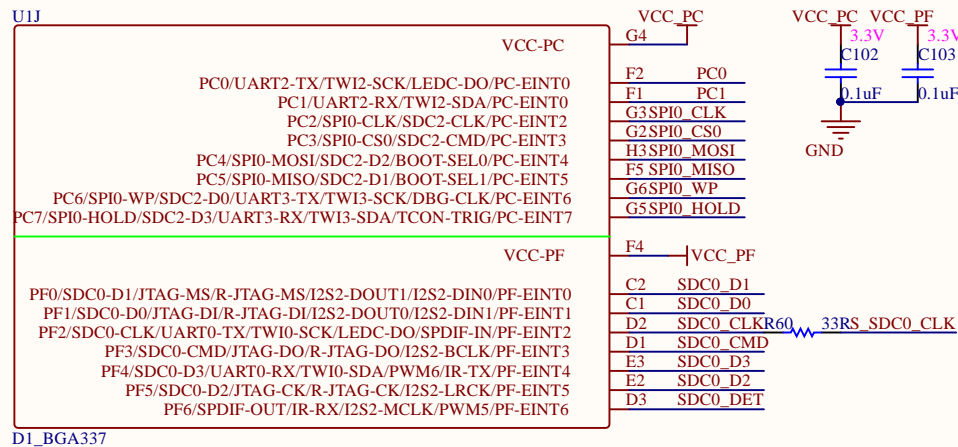
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# SODIMM\_DDR4 260P

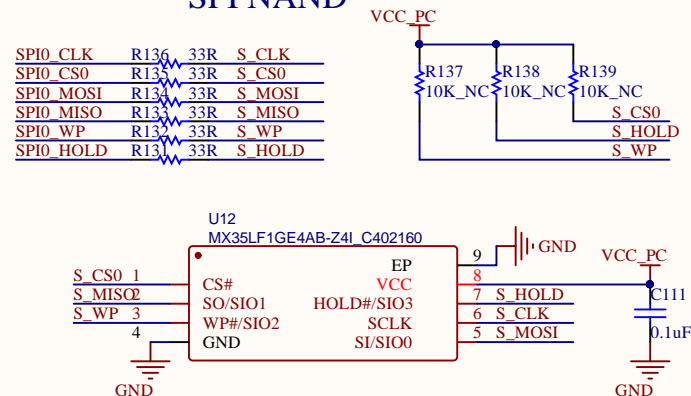


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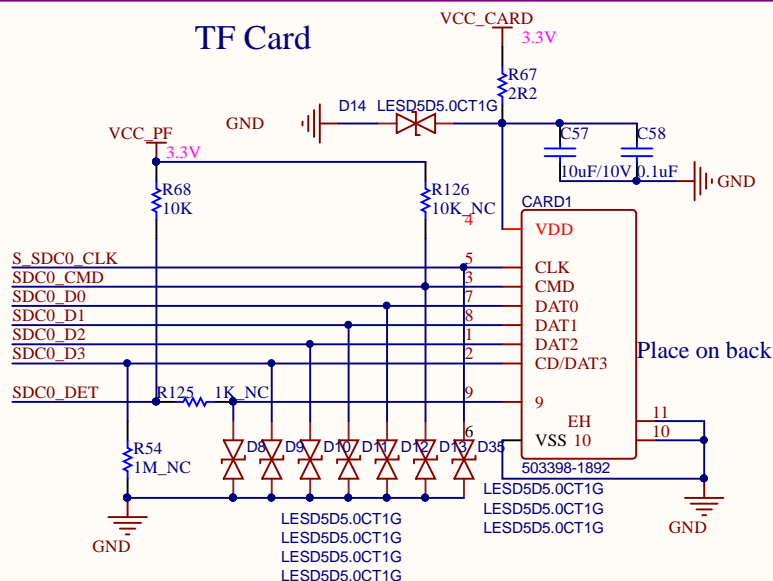
## D1 SDIO



## SPI NAND

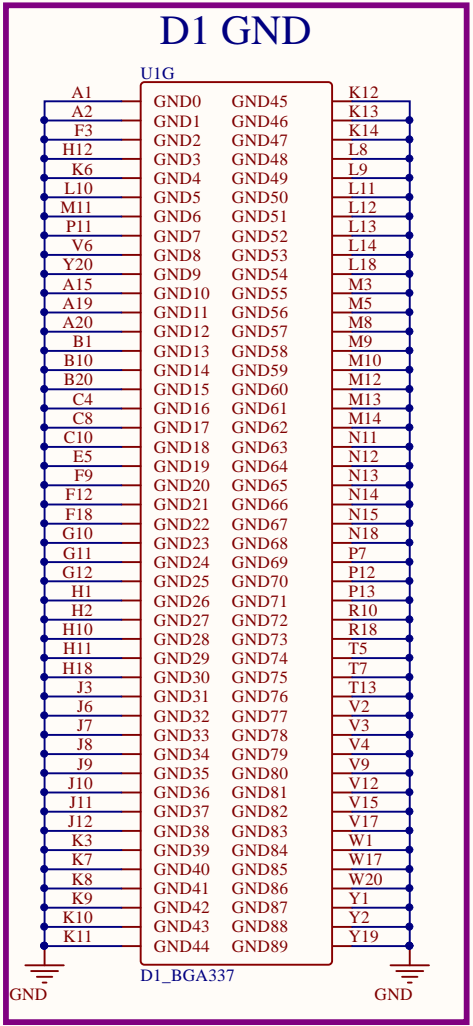
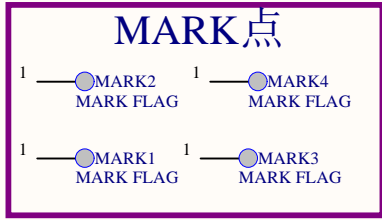
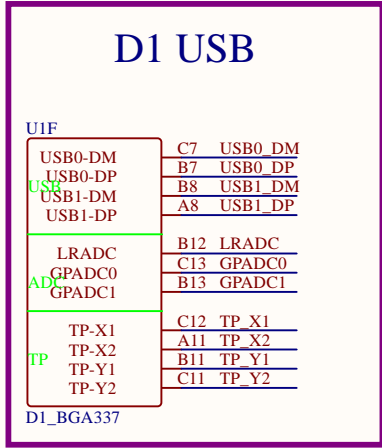
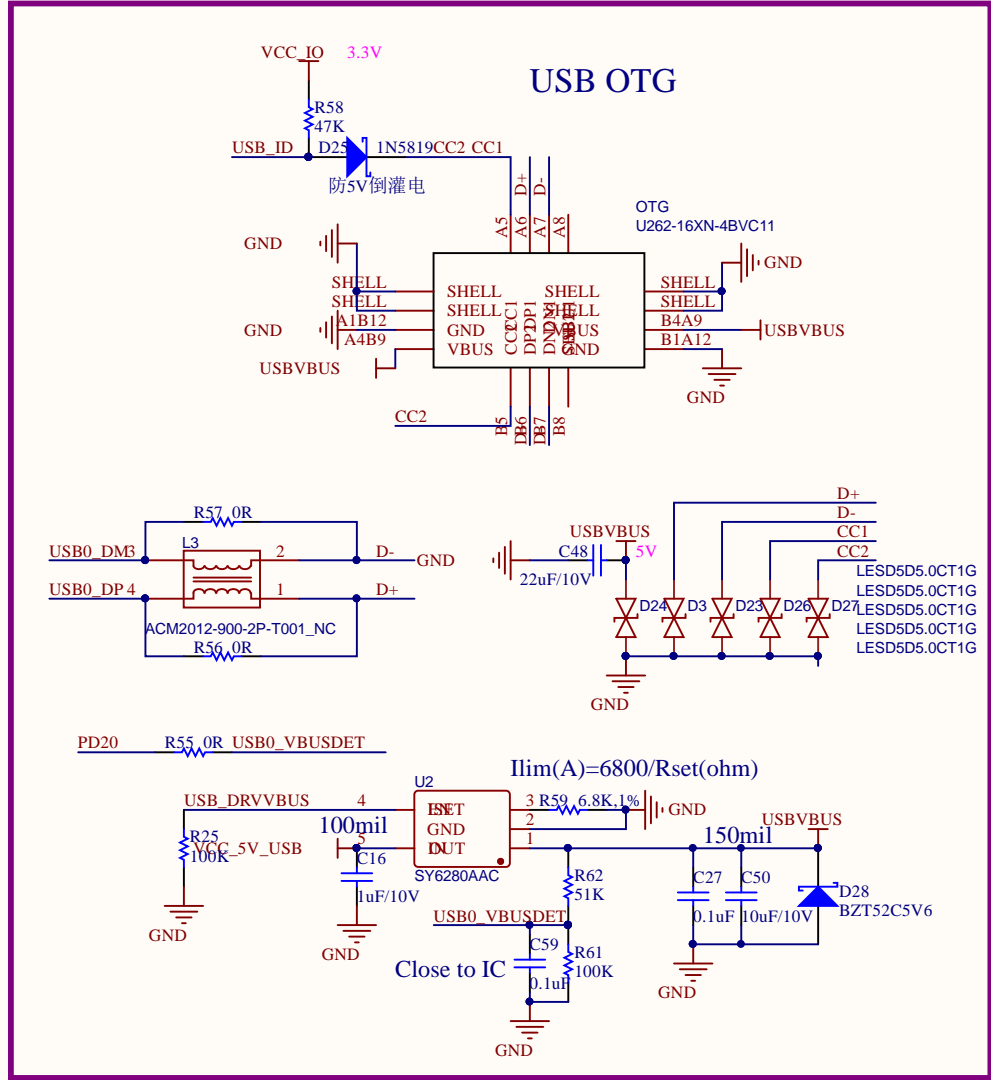


## TF Card



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